

Product Change Notification / SYST-09XEHL870

ח	2	ŧ	Δ	•
u	а	L	ᆫ	

10-Aug-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Document Change

Notification Subject:

ERRATA - PIC16(L)F15313/23 Family Silicon Errata and Data Sheet Clarification

Affected CPNs:

SYST-09XEHL870_Affected_CPN_08102023.pdf SYST-09XEHL870_Affected_CPN_08102023.csv

Notification Text:

SYST-09XEHL870

Microchip has released a new Errata for the PIC16(L)F15313/23 Family Silicon Errata and Data Sheet Clarification of devices. If you are using one of these devices please read the document located at PIC16(L)F15313/23 Family Silicon Errata and Data Sheet Clarification.

Notification Status: Final

Description of Change: Updated data sheet revision to revision E. Removed Data Sheet Clarifications for previous revision.

Impacts to Data Sheet: None

Reason for Change: To improve productivity

Change Implementation Status: Complete

Date Document Changes Effective: 10 Aug 2023

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: $\ensuremath{\mathsf{N}}/\ensuremath{\mathsf{A}}$

Attachments:	
PIC16(L)F15313/23 Family Silicon Errata and Data Sheet Clarification	
Please contact your local Microchip sales office with questions or concerns re	egarding this notification.
Terms and Conditions:	
If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN emhome page select register then fill in the required fields. You will find instruct Microchips PCN email service in the <u>PCN FAQ</u> section.	
If you wish to <u>change your PCN profile</u> , <u>including opt out</u> , please go to the <u>PCN</u> and sign into your myMicrochip account. Select a profile option from the left the applicable selections.	

Affected Catalog Part Numbers (CPN)

PIC16F15313-E/SN

PIC16F15313-E/SNVAO

PIC16F15313-E/P

PIC16F15313-E/RF

PIC16F15313-E/RFVAO

PIC16F15313-I/SNC01

PIC16F15313-I/SN

PIC16F15313-I/SNVAO

PIC16F15313-I/P

PIC16F15313-I/RF

PIC16F15313T-I/SN020

PIC16F15313T-I/SN021

PIC16F15313T-I/SNC01

PIC16F15313T-I/SN

PIC16F15313T-I/RF

PIC16F15313T-E/SN

PIC16F15313T-E/SNVAO

PIC16F15313T-E/RF024

PIC16F15313T-E/RF026

PIC16F15313T-E/RF028

PIC16F15313T-E/RFVAO

PIC16LF15313-E/SN

PIC16LF15313-E/SNVAO

PIC16LF15313-E/P

PIC16LF15313-E/RF

PIC16LF15313-I/SN

PIC16LF15313-I/P

PIC16LF15313-I/RF

PIC16LF15313T-I/SN023

PIC16LF15313T-I/SN

PIC16LF15313T-I/RF

PIC16LF15313T-E/SNVAO

PIC16LF15313T-E/RFVAO

PIC16F15323-E/P

PIC16F15323-E/SL

PIC16F15323-E/SLVAO

PIC16F15323-E/ST

PIC16F15323-E/STVAO

PIC16F15323-E/JQ

PIC16F15323-I/P

PIC16F15323-I/SL

PIC16F15323-I/ST

PIC16F15323-I/JQ

PIC16F15323-I/JQVAO

PIC16F15323T-I/SL

PIC16F15323T-I/ST

Date: Wednesday, August 09, 2023

$SYST-09XEHL870-ERRATA-PIC16 (L)F15313/23\ Family\ Silicon\ Errata\ and\ Data\ Sheet\ Clarification$

PIC16F15323T-I/JQ

PIC16F15323T-E/ST022

PIC16F15323T-E/ST025

PIC16F15323T-E/ST027

PIC16F15323T-E/ST029

PIC16F15323T-E/ST

PIC16F15323T-E/STV02

PIC16F15323T-E/STVAO

PIC16F15323T-E/JQ

PIC16LF15323/SD02

PIC16LF15323-E/7NVAO

PIC16LF15323-E/P

PIC16LF15323-E/SL

PIC16LF15323-E/ST

PIC16LF15323-E/JQ

PIC16LF15323-I/P

PIC16LF15323-I/SL

PIC16LF15323-I/ST

PIC16LF15323-I/JQ

PIC16LF15323T-I/SL

PIC16LF15323T-I/ST

PIC16LF15323T-I/JQ

PIC16LF15323T-E/7NV01

PIC16LF15323T-E/JQ



PIC16(L)F15313/23

PIC16(L)F15313/23 Family Silicon Errata and Data Sheet Clarification

The PIC16(L)F15313/23 family devices that you have received conform functionally to the current Device Data Sheet (DS40001897**E**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1. The silicon issues are summarized in Table 2.

The errata described in this document will be addressed in future revisions of the PIC16(L)F15313/23 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of Table 2 apply to the current silicon revision (A4).

Data Sheet clarifications and corrections start on page 6, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB® X IDE and Microchip's programmers, debuggers, and emulation tools, which are available at the Microchip corporate website (www.microchip.com).

For example, to identify the silicon revision level using MPLAB X IDE in conjunction with a hardware debugger:

- Using the appropriate interface, connect the device to the hardware debugger.
- 2. Open an MPLAB X IDE project.
- 3. Configure the MPLAB X IDE project for the appropriate device and hardware debugger.
- 4. For MPLAB X IDE, select <u>Window > Dashboard</u> and click the **Refresh Debug Tool Status** icon ().
- Depending on the development tool used, the part number and Device Revision ID value appear in the **Output** window.

Note: If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The DEVREV values for the various PIC16(L)F15313/23 silicon revisions are shown in Table 1.

TABLE 1: SILICON DEVREV VALUES

Part Number	Device ID ⁽¹⁾	Revision ID for Silicon Revision ⁽²⁾					
Part Number	Device iD(*)	A2	A3	A4			
PIC16F15313	C16F15313 30BEh		2003h	2004h			
PIC16LF15313	30BFh	2002h	2003h	2004h			
PIC16F15323 30C0h		2002h	2003h	2004h			
PIC16LF15323	30C1h	2002h	2003h	2004h			

- **Note 1:** The Device IDs (DEVID and DEVREV) are located at addresses 8006h and 8005h, respectively. They are shown in hexadecimal in the format "DEVID DEVREV".
 - **2:** Refer to the "PIC16(L)F153XX Memory Programming Specification" (DS40001838) for detailed information on Device and Revision IDs for your specific device.

TABLE 2: SILICON ISSUE SUMMARY

Module	Facture	Item	Janua Cumamamu	Affecte	d Revis	ions ⁽¹⁾
Module	Feature	Number	Issue Summary	A2	А3	A4
	SMBus 2.0	1.1	The maximum V _I L level changes when V _{DD} is below 4.0V at 125°C.	Х	_	_
Electrical	Fixed Voltage Reference (FVR) Accuracy	1.2	FVR output tolerance may be higher than specified at temperatures below – 20°C.	Х	Х	Х
Specifications	LF Device		VDDMIN specifications are changed for LF devices only.	Х	Х	Х
	ADC Offset Error	1.5	ADC Offset Error specification changed.	Х	Х	Х
Comparator Input Pin		2.1	Negative Input Pin on RA4 is not functional.	Х	_	_
WO Do d	SMBus 2.0	3.1	SMBus 2.0 levels are not functional on the default I ² C function pins for SCL and SDA.		_	_
I/O Port	I ² C Driver	3.2	I ² C levels are not functional on the default I ² C function pins for SCL and SDA.	Х	_	_
Nonvolatile Memory (NVM)	WRERR Bit Operation	4.1	WRERR Bit Operation.	Х	Х	_
Windowed Watchdog Timer (WWDT)	<u> </u>		The Window feature of the WWDT does not operate correctly in DOZE mode.	Х	Х	_
Host Synchronous Serial Port (MSSP) SPI Client Mod		6.1	SSPBUF may become corrupted.	Х	Х	_
Digital-to-Analog (DAC)	Debug Mode	7.1	FVR as the Positive Voltage Source is not functional in Debug mode.	Х	Х	Х

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

Silicon Errata Issues

Note:

This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (A4).

1. Module: Electrical Specifications

1.1 SMBus 2.0 VIL Level

At 125°C when the VDD voltage level supplied to the device is 4.0V and above, the maximum SMBus 2.0 voltage level for the VIL parameter is 0.8V. When VDD drops below 4.0V, the maximum SMBus voltage level for VIL drops to 0.7V. This issue applies to extended temperature devices only.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Χ					

1.2 Fixed Voltage Reference (FVR) Accuracy

At temperatures below -20°C, the output voltage for the FVR may be greater than the levels specified in the data sheet. This will apply to all three gain amplifier settings (1X, 2X, 4X). The affected parameter numbers found in the data sheet are: FVR01 (1X gain setting), FVR02 (2X gain setting), and FVR03 (4X gain setting).

Work around

None.

Affected Silicon Revisions

	A2	А3	A4			
ĺ	Χ	Χ	Χ			

1.4 Minimum VDD Specifications for LF Device

VDDMIN at -40°C and +25°C = 2.3V. (See **TABLE 37-1: Supply Voltage** on page 5 for reference.)

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Х	Х	Χ			

1.5 ADC Offset Error

The table containing the Offset Error specification (AD04:EOFF) for the Analog-to-Digital Converter is modified. The updated value for Offset Error specification is +/-3.0 LSb.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Χ	Х	Х			

2. Module: Comparator

2.1 Input Pin

The negative input pin for the C1 Comparator, on RA4, is not functional on the PIC16(L)F15313 devices.

Work around

Use another negative input pin for the C1 comparator.

Affected Silicon Revisions

A2	А3	A4			
Χ					

3. Module: I/O Port

3.1 SMBus 2.0

The SMBus 2.0 signal levels are not available on the default I²C function pins on PORTA for SCL and SDA on the PIC16(L)F15313. Standard ST and TTL levels are still available for these pins, which are configurable through the INLVLA register settings.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Χ					

3.2 I²C Drivers

The I²C signal levels are not available on the default I²C function pins on PORTA for SCL and SDA on the PIC16(L)F15313. Standard ST and TTL levels are still available for these pins, which are configurable through the INLVLA register settings.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Χ					

4. Module: Nonvolatile Memory (NVM)

4.1 WRERR Bit Operation

When a Reset is issued while an NVM high-voltage operation is in progress, the WRERR bit in the NVMCON1 register is set as expected. After clearing the WRERR bit, if a Reset reoccurs, the WRERR bit is set again, regardless of whether an NVM operation is in progress or not. A successful write operation will clear the WRERR condition.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Χ	Х				

5. Module: Windowed Watchdog Timer (WWDT)

5.1 Window Feature of the WWDT Does Not Operate Correctly in DOZE Mode

When the Windowed mode of operation is enabled in DOZE mode, a window violation error is issued even though the window is open and has been armed. This condition occurs only when the window size is set to a value other than 100% open.

Work around

Method 1

Use the Windowed mode of operation in any other mode than DOZE. If disabling the DOZE mode is not an option, use the WWDT module without the window being enabled.

Method 2

If the device is in DOZE mode, perform the arming process for the window in NORMAL mode, and return to the DOZE mode.

Method 3

If there is an ISR in the application code, the arming within the window can be done inside the ISR with the ROI bit of the CPUDOZE register being set.

Affected Silicon Revisions

	A2	А3	A4			
Ī	Χ	Χ				

6. Module: Host Synchronous Serial Port (MSSP)

6.1 SSPBUF May Become Corrupted

When operating in SPI Client mode, if the incoming SCK clock signal arrives during any of the conditions below, the SSPBUF transmit shift register may become corrupted. The transmitted client byte cannot be ensured to be correct, and the state of the WCOL bit may or may not indicate a write collision.

These conditions include:

- · A write to an SFR
- · A write to RAM following an SFR read
- · A write to RAM prior to an SFR read

Work around

- 1. Connect the SS line to both the SS input and either an INT or IOC input pin.
- 2. Enable INT or IOC interrupts (interrupt on falling edge if available, otherwise check that $\overline{SS} == 0$ when the interrupt occurs).
- B. Load SSPBUF with the data to be transmitted.
- 4. Continue program execution.
- 5. When the Interrupt Service Routine (ISR) is invoked, do either of the following:
 - Add a delay that ensures the first SCK clock will be complete, or
 - Poll SSPSTAT.BF (while (BF == 0)) and wait for the transmission/reception to complete.

Once either of these is complete, it is safe to return to program execution.

Method 2 (Bit Polling Based Using SS):

- 1. Load SSPBUF with the data to be transmitted.
- 2. Poll the \overline{SS} line and wait for the \overline{SS} to go active (SS(!PORTx.nSS == 0)).
- 3. When \overline{SS} is active ($\overline{SS} == 0$), do either of the following:
 - Add a delay that ensures the first SCK clock will be complete, or
 - Poll SSPSTAT.BF (while (BF == 0)) and wait for the transmission/reception to complete.

Once one of these two methods is complete, it is safe to return to program execution.

Method 3 (SS Not Available):

- 1. Load SSPBUF with the data to be transmitted.
- 2. Poll SSPSTAT.BF (while (BF == 0)), and wait for the transmission/reception to complete.

Affected Silicon Revisions

A2	А3	A4			
Χ	Χ				

7. Module: Digital-to-Analog (DAC)

7.1 FVR as the Positive Voltage Source Is Not Functional in Debug Mode

When using the DAC module while in Debug mode, and selecting the FVR as the positive voltage source, DAC1PSS = 10, the DAC is not functional and unexpected results can be seen on the output.

Work around

None.

Affected Silicon Revisions

A2	А3	A4			
Х	Х	Х			

TABLE 37-1: SUPPLY VOLTAGE

PIC16LF15313/23				Standard Operating Conditions (Unless Otherwise Stated)				
Param. No.	Sym.	Characteristic	Min.	Тур.†	Max.	Units	Conditions	
D002	VDD		1.8 2.3 2.5	_ _ _	3.6 3.6 3.6	V V V	$\begin{aligned} & Fosc \leq 16 \text{ MHz, } +25^{\circ}\text{C} \leq \text{Ta} \leq +125^{\circ}\text{C} \\ & Fosc \leq 16 \text{ MHz, } -40^{\circ}\text{C} \leq \text{Ta} \leq +25^{\circ}\text{C} \\ & Fosc > 16 \text{ MHz} \end{aligned}$	

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS40001897**E**):

Note: Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

APPENDIX A: DOCUMENT REVISION HISTORY

Rev F Document (08/2023)

Updated data sheet revision to revision E. Removed Data Sheet Clarifications for previous revision.

Rev E Document (03/2021)

Updated Table 2 and 37-1 and Section 1.4 Minimum VDD Specifications. Other minor corrections.

Data Sheet Clarifications:

Added Module 1.2: Figure 37-5 Clock Timing and 1.3: Figure 37-9 Brown-Out Reset Timing and Characteristics.

Rev D Document (11/2020)

Added Table 37-1 and Module 1.5; Updated Table 2 and Module 1.4. Other minor corrections.

Rev C Document (01/2019)

Added Affected Silicon Revision A4. Added Modules 1.4, 4, 5, 6, and 7. Other minor corrections.

Data Sheet Clarifications:

Added Module 1: Electrical Specifications; Correction to Table 37-14.

Rev B Document (08/2017)

Added Affected Silicon Revision A3. Other minor corrections.

Rev A Document (04/2017)

Initial release of this document.

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
 mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to
 continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at https://www.microchip.com/en-us/support/design-help/client-support-services.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, TrueTime, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, GridTime, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, KoD, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach. Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2017-23, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-1525-5

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199

Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support
Web Address:

www.microchip.com

Atlanta Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi, MI

Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Iel: 281-894-59 Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000

China - Chengdu Tel: 86-28-8665-5511

China - Chongqing Tel: 86-23-8980-9588

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen

Tel: 86-755-8864-2200

China - Suzhou Tel: 86-186-6233-1526

China - Wuhan Tel: 86-27-5980-5300

China - Xian Tel: 86-29-8833-7252

China - Xiamen Tel: 86-592-2388138

China - Zhuhai Tel: 86-756-3210040

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631

India - Pune

Tel: 91-20-4121-0141

Japan - Osaka

Tel: 81-6-6152-7160

Japan - Tokyo Tel: 81-3-6880- 3770

Korea - Daegu Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu Tel: 886-3-577-8366

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

EUROPE

Austria - Wels Tel: 43-7242-2244-39

Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4485-5910 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris Tel: 33-1-69-53-63-20

Fax: 33-1-69-30-90-79 **Germany - Garching**

Tel: 49-8931-9700 **Germany - Haan** Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-72400

Germany - Karlsruhe Tel: 49-721-625370

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611

Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7288-4388

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

UK - Wokingham Tel: 44-118-921-5800 Fax: 44-118-921-5820